

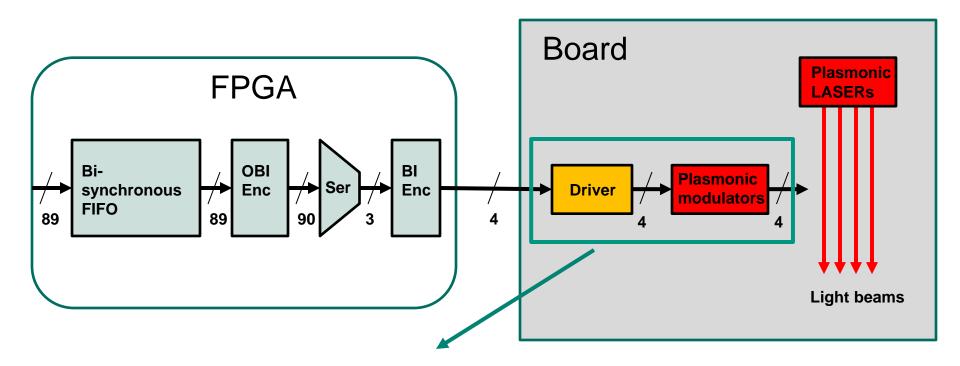
## NAVOLCHI TelConf. 14.10.2013

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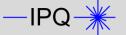
## **NAVOLCHI** Demonstrator Implementation





**Electronics / plasmonics interface?** 

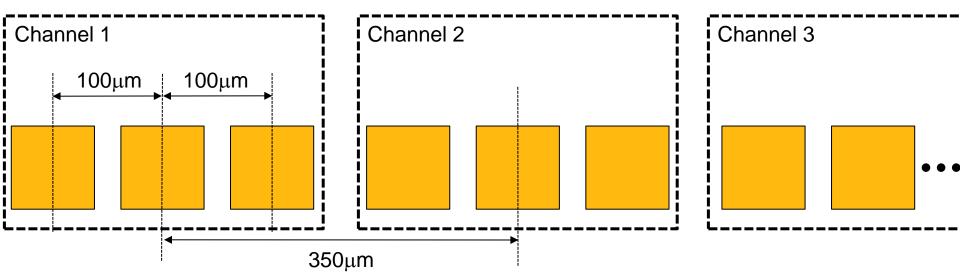
Origin: STMicroelectronics Progress Report, NAVOLCHI Phone Conference 19, September 23, 2013



#### Interface between Electronics and Plasmonics

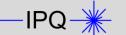


### Gold contact pads



# MZM Specs

- No 50Ω termination
- High impedance devices with C≈ 10 20 fF
- Driving voltage up to 10V might be needed
- Total electrode length ≈ 120µm → no additional latency



#### Interface between Electronics and Plasmonics



#### Questions

- Is wire bonding possible?
  - Very thin and small contact pads
  - GSG configuration with 100μm pitch
- What is the distance between the driver and the modulator chip?

